



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-01-16
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Floriana SAN BIAGIO	Representative title	APMS Material Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
	G38P*BRG9AV2	A	3068-SH1A	2025-01-16
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	1540	mg	Each	ECOPACK® 1
Identity	Authority			
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
1	245	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM01083789/1F147595	
Package designator	Package size	Number of instances	Shape	
SIP	10.2x9.15	7	gull wing	
Comment				
Comment	A08P H2PAK-7; MDF is valid for SCT029H75G3AG			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
QUERY		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
QUERY		Response
1 - Product(s) meets EU ELV requirements without any exemptions		false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
Exemption Id.	Description	
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 17th Nov 2023				Response
QUERY				Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen				false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				true
Substance	amount in product (mg)	Application	ppm in product	
Nickel	1.277	alloy	829	
Lead	4.570	soft solder	2968	
Lead-Borate Glass	0.000		0	
Lead Zirconate Titanate	0.000		0	
Antimony trioxide	0.000		0	
Bisphenol A	0.000		0	

QueryList :Customer		Response
QUERY		Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
X	O	O	O	O	
Soft solder					
Homogeneous Material(s) containing Lead					

QueryList : REACH-7th November 2024					Response
QUERY					Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					false
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
Lead (Pb)	1000ppm	4.57	Soft solder	2968	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material	
Lead (Pb)	1000ppm	4.57	Soft solder	954868	



QueryList : Responsible metals sourcing	Response
QUERY	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	true

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	G38P*BRG9AV2		1540.0000		6999998.0	1000002.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	8.199	mg	supplier	die	Silicon(Si)	7440-21-3		0.034	mg	4147	22
	M-011 Other inorganic materials			California 65	die	Silicium carbide	409-21-2		7.685	mg	937309	4990
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.140	mg	17075	91
				supplier	metallisation	Copper(Cu)	7440-50-8		0.019	mg	2317	12
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.120	mg	14636	78
				supplier	metallisation	Silver(Ag)	7440-22-4		0.123	mg	15002	80
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.015	mg	1829	10
				supplier	metallisation	Vanadium(V)	7440-62-2		0.004	mg	488	3
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.022	mg	2683	14
				supplier	passivation	Silicon oxide	7631-86-9		0.037	mg	4513	24
Leadframe	M-004 Copper and its alloys	1032.280	mg	supplier	alloy	Copper(Cu)	7440-50-8		1029.759	mg	997558	668675
				supplier	alloy	Iron phosphide	26508-33-8		0.866	mg	839	562
				supplier	alloy	Iron(Fe)	7439-89-6		0.474	mg	459	308
				supplier	metallization	Nickel(Ni)	7440-02-0		1.157	mg	1121	751
				supplier	metallization	Phosphorus metal	7723-14-0		0.024	mg	23	16
Soft solder	Solder	4.786	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	4.570	mg	954868	2968
				supplier	solder	Silver(Ag)	7440-22-4		0.120	mg	25073	78
				supplier	solder	Tin(Sn)	7440-31-5		0.096	mg	20059	62
Bonding wires	M-003 Aluminum and its alloys	6.567	mg	supplier	wire	Aluminium (Al)	7429-90-5		6.567	mg	1000000	4264
Bonding wires 2	M-003 Aluminum and its alloys	0.273	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.272	mg	996337	177
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	3663	1
				supplier	wire							
Encapsulation	M-015 Other organic materials	485.619	mg	supplier	mold compound	Silica vitreous	60676-86-0		417.632	mg	859999	271190
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		12.141	mg	25001	7884
				supplier	mold compound	Phenol resin	1985-51-9		19.425	mg	40000	12614
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		4.856	mg	10000	3153
				supplier	mold compound	Antimony trioxide	proprietary		19.425	mg	40000	12614
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		9.712	mg	19999	6306
				supplier	mold compound	Carbon black	1333-86-4		2.428	mg	5000	1577
Connections coating	Solder	2.276	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		2.276	mg	1000000	1478